Spec. No.: RLP-K-HTS-0001 /12

Date: 2017. 4. 21

Data sheet

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

Style: RLP16,20,32,63, MLP20,32,63

AEC-Q200 qualified

RoHS COMPLIANCE ITEM Halogen and Antimony Free

Note: • Stock conditions

Temperature: $+5^{\circ}\text{C} \sim +35^{\circ}\text{C}$ Relative humidity: $25\% \sim 75\%$

The period of guarantee: Within 2 year from shipmen t by the company.

Solderability shall be satisfied.

- Product specification contained in this data sheet are subject to change at any time without notice
- •If you have any questions or a Purchasing Specification for any quality Agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya

/12

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

RLP16, 20, 32, 63, MLP20,32, 63 Page: 1/24

1. Scope

1.1 This data sheet covers the detail requirements for metal-plate chip resistor; low ohm, style of RLP16, 20, 32, 63, MLP20,32, 63.

1.2 Applicable documents

JIS C 5201-1: 2011, JIS C 5201-8: 2014, JIS C 5201-8-1: 2014 IEC60115-1: 2008, IEC60115-8: 2009, IEC60115-8-1: 2014

2. Classification

Type designation shall be the following form.

(Example)

1 Metal - plate chip resistor; low ohm

2 Size

RLP16	1608 size, 0.33W
RLP20	2012 size, 0.5W
RLP32	3216 size, 1W
RLP63	6332 size, 1W
MLP20	2012 size, 1W
MLP32	3216 size, 1.5W
MLP63	6332 size, 2W

3 Temperature coefficient of resistance

N	±70×10 ⁻⁶ /°C
K	±100×10 ⁻⁶ /°C
-(Dash)	±150×10 ⁻⁶ /°C

4 Rated resistance

1L50	$1.5 m\Omega$
R002	2mΩ

5 Tolerance on rated resistance

F	±1%
J	±5%

6 Packaging form

TP	Paper taping
TE	Embossed taping

RLP16, 20, 32, 63, MLP20,32, 63 Page: 2/24

3. Rating

3.1 The ratings shall be in accordance with Table-1.

3.1.1 RLP series

Table-1(1)

Style	Rated dissipation	Rated current	Temperature	coefficient of	Rated resistance	Tolerance on rated	
Otylo	(W)	(A)	resistance		$(m\Omega)$	resistance	
		8.1	K	100	5		
RLP16	0.33	0.1	N	±70	3		
KLFIO	0.55	5.7	K	100	10		
		5.7	N	±70	10		
		15.8	K	100	2		
		15.6	N	±70	2		
		10.0	K	100	2		
		12.9	N	±70	3	F(±1%) J(±5%)	
	RLP20 0.5	44.4	K	100	4		
		11.1	N	±70			
		10.0	K	100	5		
			N	±70			
RI P20		RLP20 0.5	9.1	K	100	6	
1 (2) 20		9.1	N	±70	U		
		8.4	K	100	7		
		0.4	N ±70	/			
		7.0	K	100	8		
		7.9	N	±70			
		7.4	K	100	0		
			N	±70	9		
		7.0	K	100	10		
			7.0	N	±70	10	

METAL-PLATE CHIP RESISTOR; LOW OHM

RLP16, 20, 32, 63, MLP20,32, 63 3/24 Page:

Table-1(2)

	1 5	1 5	Table		D	1
Style	Rated dissipation	Rated current	Temperature	coefficient of	Rated resistance	Tolerance on rated
<u> </u>	(W)	(A)	resistance	r'	$(m\Omega)$	resistance
		31.6	-(Standard)	±150	1	
		01.0	K	±100	'	
		22.3	K	±100	2	
		22.5	N	±70		
		18.2	K	±100	3	
		10.2	N	±70	3	
		15.8	K	±100	4	
		15.0	N	±70	4	
		14.1	K	±100	5	
		14.1	N	±70	5	
		12.9	K	±100	6	F(±1%) J(±5%)
	LP32 1.0	12.9	N	±70		
		11.9	K	±100	7	
			N	±70	7	
DI Daa		1.0 11.1 10.5	K	±100	- 8	
KLF32			N	±70		
			K	±100	9	
			N	±70		
		10	K	±100	10	
			N	±70	10	
		0.5	K	±100	44	
		9.5	N	±70	11	
		0.4	K	±100	40	
		9.1	N	±70	12	
			K	±100	40	
	8.7	N	±70	13		
		0.4	K	±100	4.4	1
		8.4	N	±70	14	
		0.4	K	±100	45	1
		8.1	N	±70	15	

METAL-PLATE CHIP RESISTOR; LOW OHM

RLP16, 20, 32, 63, MLP20,32, 63 4/24 Page:

Table-1(3)

Style	Rated dissipation (W) 2.0	Rated current (A) 44.7 22.3 18.2	Temperature resistance -(Standard) K N K N K N K	(10 ⁻⁶ / °C) ±150 ±100 ±70 ±100 ±70	Rated resistance (mΩ) 1	Tolerance on rated resistance
Ciyic	, ,	44.7	-(Standard) K N K N K N	±150 ±100 ±70 ±100 ±70	1	resistance
	2.0	22.3	K N K N K	±100 ±70 ±100 ±70		
_	2.0	22.3	N K N K	±70 ±100 ±70		
			K N K	±100 ±70	2	
			N K	±70	2	
			K		2	
		18.2				
		10.2		±100	3	
			N	±70	3	
		15.8	K	±100	4	
		0.01	N	±70	4	
		14.1	K	±100	5	
		14.1	N	±70	ວ	_
		12.9	K	±100	6	
	12.9	N	±70	O		
		11.9	K	±100	7]
	11.9	N	±70	,	E(±10/)	
RLP63	LP63	11.1	K	±100	8	F(±1%) J(±5%)
			N	±70	0	
		10.5	K	±100	9	
			N	±70	9	
		10	K	±100	10	
	10	N	±70	10		
		0.5	K	±100	11	
	9.5	N	±70	ŢŢ		
		9.1	K	±100	10	
		9.1	N	±70	12	
		0.7	K	±100	12	
		8.7	N	±70	13	
		0.4	K	±100	1.1	
		8.4	N	±70	14	
		0.4	K	±100	15	
	8.1	N	±70	15		

RLP16, 20, 32, 63, MLP20,32, 63 Page: 5/24

3.1.2 MLP series

Table-1(4)

Style	Rated dissipation	Rated current	Temperature	coefficient of	Rated resistance	Tolerance on rated					
Style	(W)	(A)	resistance (10 ⁻⁶ / °C)		(m Ω)	resistance					
		22.3	K	100	2						
		22.5	N	±70	2						
		18.2	K	100	3						
		10.2	N	±70	3						
		15.8	K	100	4						
		15.6	N	±70	4						
		14.1	K	100	5						
		14.1	N	±70	5						
MLP20	1.0	12.9	K	100	6	F(±1%)					
IVILFZU	1.0	12.9	N	±70	В	J(±5%)					
		44.0	K	100	7						
		11.9	N	±70	/						
		44.4	K	100	0						
		11.1	N	±70	8						
							10.5	K	100	9	
		10.5	N	±70] 9						
		10	K	100	- 10						
		10	N	±70							
		38.7	-(Standard)	±150	- 1						
			N	±70							
		27.3	K	±100	2						
		21.3	N	±70	2						
			22.3	K	±100	3					
		22.3	N	±70	3						
		10.2	K	±100	4						
		19.3	N	±70	4						
	MLP32 1.5					17.2	K	±100	E		
MI Doo		17.3	N	±70	5	F(±1%) J(±5%)					
IVILITOZ		15.8	K	±100	6						
		13.0	N	±70	· · ·						
		14.6	K	±100	7						
		14.0	N	±70	/						
		12.6	K	±100	o						
		13.6	N	±70	8						
		12.0	K	±100	9						
		12.9	N	±70	9						
		10.0	K	±100	10						
		12.2	N	±70	10						

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

RLP16, 20, 32, 63, MLP20,32, 63 Page: 6/24

Table-1(5)

	Data d dissination	Data d au urranat	Tananaratura	· '	Dated registeres	Toloronoo on rotod	
Style	Rated dissipation	Rated current	Temperature	COEIIICIENT OF	Rated resistance	Tolerance on rated	
	(W)	(A)	resistance		(mΩ)	resistance	
		63.2	K	100	0.5	J(±5%)	
		00.2	N	±70	0.0	G (= G 76)	
		36.5	K	100	1.5		
		30.3	N	±70	1.0		
		31.6	K	100	2		
		31.0	N	±70	2		
		20.2	K	100	2.5		
		28.2	N	±70	2.5	F(±1%) J(±5%)	
		05.0	K	100	0		
	MLP63 2.0	25.8	N	±70	3		
		22.3	K	100	4		
MI DOO			N	±70			
IVILP63		20	K	100	E		
			N	±70	5		
		18.2	K	100	6		
			N	±70	6		
		40.0	K	100	7		
		16.9	N	±70			
			45.0	K	100	_	1
		15.8	N	±70	8		
			K	100	_	1	
		14.9	N	±70	9		
			K	100		1	
		14.1	N	±70	10		
			17	±10		1	

Style	Isolation voltage (V)	Category temperature range (°C)
RLP16	, ,	, ,
RLP20		
RLP32		
RLP63	100	<i>–</i> 55~+155
MLP20		
MLP32		
MLP63		

3.2 Climatic category

55/155/56 Lower category temperature -55 °C Upper category temperature +155 °C +155 °C

Duration of the damp heat, steady state test 56days

3.3 Stability class

5% Limits for change of resistance:

-for long–term tests $\pm 5\%$ -for short–term tests $\pm 1\%$

/12

RLP16, 20, 32, 63, MLP20,32, 63 Page: 7/24

3.4 Derating

The derated values of dissipation at temperature in excess of 70 °C shall be as indicated by the following curve.

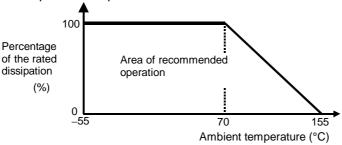


Figure-1 Derating curve

3.5 Rated voltage

d.c. or a.c. r.m.s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

$$E = \sqrt{P \cdot R}$$

E: Rated voltage (V)

P: Rated dissipation (W)

R: Rated resistance (Ω)

3.6 Rated current

The rated current calculated from the square root of the quotient of the rated resistance and the rated dissipation.

I: Rated current (A)

P: Rated dissipation (W)

R: Rated resistance (Ω)

The rated current shall be corresponding to rated voltage.

4. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

Symbol	Pac	ckaging form	Standard packaging quantity / units	Application
TP	Paper taping 8mm width, 4mm pitches		5,000 pcs.	RLP16, 20, 32, MLP20,32
TE	Embossed taping	12mm width, 4mm pitches	4,000 pcs.	RLP63, MLP63

RLP16, 20, 32, 63, MLP20,32, 63 Page: 8/24

5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure-2 and Table-3.

5.1.1 RLP series

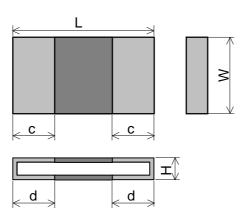


Figure-2

Table–3(1) Unit: mm

		iai	oie-3(1)			Unit: mm
Style	Rated resistance (m Ω)	L	W	Н	С	d
RLP16	5	16.01	00.01	0.35±0.10	0.2±0.1	0.6±0.1
KLPIO	10	1.6±0.1	0.8±0.1	0.3±0.1	0.2±0.1	0.3±0.1
	2			0.22±0.10	0.35±0.10	0.55±0.20
	3			0.45±0.10	0.35±0.10	0.75±0.20
	4			0.35±0.10	0.35±0.10	0.75±0.20
	5			0.35±0.10	0.35±0.10	0.6±0.2
RLP20	6	2.0±0.15	1.25±0.15	0.35±0.10	0.35±0.10	0.47±0.20
	7			0.22±0.10	±0.10 0.35±0.10	0.75±0.20
	8			0.22±0.10	0.35±0.10	0.6±0.2
	9			0.22±0.10	0.35±0.10	0.52±0.20
	10			0.22±0.10	0.35±0.10	0.47±0.20
	1			0.32±0.15	1.1±0.25	1.1±0.25
	2			0.32±0.15	0.5±0.25	0.5±0.25
	3			0.35±0.10	5±0.10 1.1±0.25	1.3±0.25
	4			0.35±0.10		1.1±0.25
	5			0.35±0.10 0.35±0.10	1.0±0.25	1.0±0.25
	6				0.85±0.25	0.85±0.25
	7			0.35±0.10	0.7±0.25	0.7±0.25
RLP32	8	3.2±0.15	1.6±0.15	0.35±0.10	0.6±0.25	0.6±0.25
	9	0		0.3±0.1	0.75±0.25	0.75±0.25
	10			0.28±0.10	0.5±0.25	0.5±0.25
	11			0.28±0.10	0.5±0.25	0.5±0.25
	12			0.22±0.10	0.65±0.25	0.65±0.25
	13			0.22±0.10	0.65±0.25	0.65±0.25
	14			0.22±0.10	0.55±0.25	0.55±0.25
	15			0.22±0.10	0.5±0.25	0.5±0.25

RLP16, 20, 32, 63, MLP20,32, 63 Page: 9/24

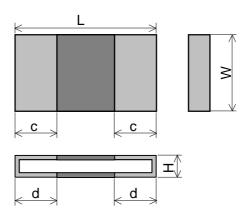


Table-3(2) Unit: mm Style W Н Rated resistance (m Ω) С d 3.2 ± 0.25 0.38±0.15 2.2±0.25 2.2±0.25 2 0.38±0.15 1.1±0.25 1.1±0.25 3 0.45±0.15 2.2±0.25 2.2±0.25 4 0.35±0.15 2.2±0.25 2.2±0.25 5 0.34 ± 0.15 1.95±0.25 1.95±0.25 6 0.34±0.15 1.75±0.25 1.75±0.25 7 0.35±0.15 1.4±0.25 1.4±0.25 1.1±0.25 1.1±0.25 RLP63 8 0.35±0.15 6.3 ± 0.25 3.1±0.25 0.35±0.15 9 0.8 ± 0.25 0.8 ± 0.25 10 0.23±0.15 1.75±0.25 1.75±0.25 11 0.23 ± 0.15 1.75±0.25 1.75±0.25 12 0.23 ± 0.15 1.4±0.25 1.4±0.25 1.3±0.25 1.3±0.25 13 0.23±0.15 14 0.23±0.15 1.1±0.25 1.1±0.25 15 0.23±0.15 0.95±0.25 0.95±0.25

RLP16, 20, 32, 63, MLP20,32, 63 10/24 Page:

5.1.2 MLP series

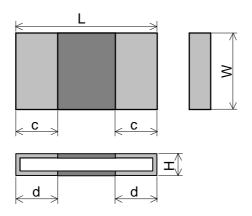


Table-3(3) Unit: mm

				1	1	Offic friin
Style	Rated resistance (m Ω)	L	W	Н	С	d
	2			0.22±0.10	0.35±0.10	0.55±0.20
	3			0.45±0.10	0.35±0.10	0.75±0.20
	4			0.35±0.10	0.35±0.10	0.7±0.2
	5			0.35±0.10	0.35±0.10	0.6±0.2
MLP20	6	2.0±0.15	1.25±0.15	0.35±0.10	0.35±0.10	0.47±0.20
	7			0.22±0.10	0.35±0.10	0.75±0.20
	8			0.22±0.10	0.35±0.10	0.6±0.2
	9			0.22±0.10	0.35±0.10	0.52±0.20
	10			0.22±0.10	0.3±0.1	0.47±0.20
	1			0.32±0.15	1.1±0.25	1.1±0.25
	2			0.32±0.15	0.5±0.25	0.5±0.25
MLP32	3			0.35±0.10	0.7±0.25	1.3±0.25
	4			0.35±0.10 0.35±0.10	1.1±0.25	1.1±0.25
	5	3.2±0.15	1.6±0.15		1.0±0.25	1.0±0.25
	6		1.0±0.13	0.35±0.10	0.85±0.25	0.85±0.25
	7			0.35±0.10	0.7±0.25	0.7±0.25
	8			0.35±0.10	0.6±0.25	0.6±0.25
	9		-	0.3±0.1	0.75±0.25	0.75±0.25
	10			0.28±0.10	0.5±0.25	0.5±0.25
	0.5			0.58±0.15	2.2±0.25	2.2±0.25
	1.5			0.38±0.15	1.5±0.25	1.5±0.25
	2			0.58±0.15	2.2±0.25	2.2±0.25
	2.5			0.45±0.15	2.4±0.25	2.4±0.25
	3			0.45±0.15	2.2±0.25	2.2±0.25
MLP63	4	62.025	3.1±0.25	0.34±0.15	2.2±0.25	2.2±0.25
IVILFO3	5	6.3±0.25	3.1±0.∠3	0.51±0.15	1.1±0.25	1.1±0.25
	6			0.5±0.15	1.1±0.25	1.1±0.25
	7			0.5±0.15	0.6±0.25	0.6±0.25
	8	1		0.35±0.15	1.1±0.25	1.1±0.25
	9			0.35±0.15	0.8±0.25	0.8±0.25
	10	1		0.35±0.15	0.5±0.25	0.5±0.25

RLP16, 20, 32, 63, MLP20,32, 63 11/24 Page:

5.2 Net weight (Reference)

Style	Rated resistance (m Ω)	Net weight (mg)
RLP16	5	2
RLP16	10	2
RLP20	2,4 to 10	3 7
KLP20	3 1	
		12
	2	11
	3	11
	4	12
	5	11
	6	11
	7	11
RLP32	8	10
	9	9
	10	9
	11	9
	12	8
	13	7
	14	7
	15	6
	1	50
		42
	<u>2</u> 3	57
	4	43
	5	43
	6	41
	7	42
RLP63	8	41
	9	40
	10	30
	11	30
	12	26
	13	26
	14	26
	15	26

RLP16, 20, 32, 63, MLP20,32, 63 Page: 12/24

5.2 Net weight (Reference)

Style	Rated resistance (m Ω)	Net weight (mg)
MLP20	2,4 to 10	3
IVILEZU	3	7
	1	12
	2	11
	3	11
	4	12
MLP32	5	11
IVILI 32	6	11
	7	11
	8	10
	9	9
	10	9
	0.5	90
	1.5	47
	2	77
	2.5	63
	3	63
MLP63	4	48
IVILFOS	5	64
	6	55
	7	55
	8	43
	9	40
	10	41

6. Marking

The Rated resistance of RLP16 should not be marked standard.

6.1 RLP63, MLP63

The rated resistance shall be marked in 4 characters consisting of 3 figures and a letter and marked on over coat side.

(Example) "R010"
$$\rightarrow$$
 0.01 [Ω] \rightarrow 10 [m Ω]

"1L50"
$$\rightarrow$$
 0.0015 [Ω] \rightarrow 1.5 [m Ω]

6.2 RLP20, 32, MLP20, 32

The rated resistance shall be marked in combination of two figures and underlines and marked on over coat side.

$$(\text{Example}) \quad \text{``}\underline{05}\text{''} \rightarrow 0.005 \ [\Omega] \rightarrow 5 \ [\text{m}\Omega]$$

"
$$\underline{10}$$
" \rightarrow 0.01 [Ω] \rightarrow 10 [m Ω]

RLP16, 20, 32, 63, MLP20,32, 63 Page: 13/24

7. Performance

7.1 The standard condition for tests shall be in accordance with Sub-clause 4.2, JIS C 5201–1: 2011.

7.2 The performance shall be satisfied in Table-4.

Table-4(1)

Table- 4(1)							
No.	Test items	C	ondition of test (JIS C 52	201–1)		Performance requirements
1	Visual examination	Sub-clause					As in 4.4.1
		Checked by visual examination.					The marking shall be legible, as
						checked by visual examination.	
2	Dimension	Sub-clause 4.4.2					As specified in Table-3 of this
	5						specification.
	Resistance		value shall be			ounting	As in 4.5.2
		the substra	te of the followin	g condit	ion.		The resistance value shall
			b Curi	ront			correspond with the rated resistance taking into account the
		Current terminal		ninal			specified tolerance.
		torrinia	*		:Copper	clad	specifica tolerarioe.
		Vo	Itage terminal		:Solder	resist	
					Unit	t:mm	
		Style	Resistance	0	b	_	
		Style	value(m Ω)	а	D	С	
		RLP16	5	0.6	0.9	0.9	
		I \Li IU	10	1.0	0.6	0.3	
		RLP20	2,3	0.5	1.1	1.36	
		- 1.2. 20	4 to 10	0.8	0.95		
			1	1.0	1.45		
			2	2.1	0.9		
		RLP32	3 4	0.8	1.55	1.7	
			5 and 6	1.0 1.4	1.45 1.25		
			7 to 15	2.1	0.9		
			1	1.5	3.0	4.0	
			2	4.0	1.8	7.0	
		RLP63	3, 4	1.8	2.9		
			5	2.4	2.6	3.5	
			6 to 15	4.0	1.8		
		MIDOO	2,3	0.5	1.1	1.06	
		MLP20	4 to 10	8.0	0.95	1.36	
			1	1.0	1.45		
			2	2.1	0.9		
		MLP32	3	0.8	1.55	1.7	
		11121 02	4	1.0	1.45	,	
			5 and 6	1.4	1.25		
			7 to 10	2.1	0.9		
		MLP63	0.5,2 to 4	1.8	2.9	3.5	
		1.5, 5 to 10 4.0 1.8					
		Thickness of copper clad: 0.035mm					
		4-Terminal method Measurement current: 1(Δ)					
		Measurement current: 1(A) Note: The measuring apparatus corresponding to					
		DC Low-ohm Mater (1A) of AX-1152D for ADEX CORPORATION.					

METAL-PLATE CHIP RESISTOR; LOW OHM

RLP16, 20, 32, 63, MLP20,32, 63 14/24 Page:

Table-4(2)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
3	Voltage proof	Sub-clause 4.7	No breakdown or flash over
3	Voltage proof	Sub-clause 4.7 Method: 4.6.1.4(See Figure–5)	INO DIEdROOWITOI IIdSITOVEI
		Test voltage: Alternating voltage with a peak value	
		of 1.42 times the insulation voltage. Duration: 60 s±5 s	
		Insulation resistance	R≥1 GΩ
			N2 1 G52
		Test voltage: Insulation voltage Duration: 1 min.	
4	Solderability	Sub-clause 4.17	As in 4.17.4.5
4	Solderability		The terminations shall be covered
		Without aging	with a smooth and bright solder
		Flux: The resistors shall be immersed in a	coating.
		non–activated soldering flux for 2 s.	Coating.
		Bath temperature: 235 °C±5 °C	
_	NA C	Immersion time: 2 s±0.5 s	
5	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
	O sada a d	Test substrate: RLP16: Figure–3–1	
	Overload (in the array water)	RLP20, MLP20 Figure-3-2	
	(in the mounted state)	RLP32 MLP32 Figure-3-3	
		RLP63, MLP63 Figure-3-4	
		Sub-clause 4.13	
		The applied voltage shall be 2.5 times the rated	
		voltage or the current corresponding to.	
		Duration: 2 s	No visible domage
		Visual examination	No visible damage ∆R ≤ ±1%
	Solvent resistance of the	Resistance	1
	marking	Sub-clause 4.30	Legible marking
	marking	Solvent: 2-propanol	
		Solvent temperature: 23 °C±5 °C	
		Method 1	
		Rubbing material: cotton wool	
		Without recovery	
6	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure-4	
	Bound strength of the end	Sub-clause 4.33	
	face plating	Bent value: 3mm(RLP16, 20, 32, MLP20, 32)	
		1 mm(RLP63, MLP63)	
		Resistance	ΔR ≤ ±1%
	Final measurements	Sub-clause 4.33.6	
		Visual examination	No visible damage

RLP16, 20, 32, 63, MLP20,32, 63 Page: 15/24

Table-4(3)

	1able-4(3)							
No	Test	t iten	าร	Condition of test (JIS C 5201–1)	Performance requirements			
7	Resistance heat	to	soldering	Sub-clause 4.18 (JEITA RC-2144 2.3.2) Substrate material: Epoxide woven glass Test substrate: Figure-3-1 T ₁ :Pre-heat minimum temp.:150±5 °C T ₂ :Pre-heat maximum temp.:180±5 °C T ₃ :Soldering temp.:220 °C T ₄ :Pre-heat duration:120±5 s t ₂ :Soldering duration:60 to 90 s t ₃ :Peak duration(T ₄ -5°C):20 to 40 s Pre-reflow soldering: 1 time (Initial measurements) Reflow soldering: 3 times				
	Component resistance		solvent	Visual examination Resistance Sub-clause 4.29 Solvent: 2-propanol Solvent temperature: 23 °C±5 °C Method 2 Recovery: 48 h Visual examination Resistance	No visible damage $\Delta R \leq \pm 1\%$ No visible damage $\Delta R \leq \pm 1\%$			
8	Mounting Adhesion			Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3-1 Sub-clause 4.32				
	Rapid chang	e ter	mperature	Force: 5 N Duration: 10 s±1 s Visual examination Sub–clause 4.19 Lower category temperature:–55 °C Upper category temperature:+155 °C Duration of exposure at each temperature: 30 min. Number of cycles: 5 cycles. Visual examination	No visible damage No visible damage			
					No visible damage $\Delta R \le \pm 1\%$			

RLP16, 20, 32, 63, MLP20,32, 63 16/24 Page:

Table-4(4)

		1able 4(4)	
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
9	Climatic sequence	Sub-clause 4.23	
	-Dry heat	Sub-clause 4.23.2	
		Test temperature: +155 °C	
		Duration: 16 h	
	-Damp heat, cycle	Sub-clause 4.23.3	
	(12+12hour cycle)	Test method: 2	
	First cycle	Test temperature: 55 °C	
		[Severity(2)]	
	-Cold	Sub-clause 4.23.4	
		Test temperature –55 °C	
		Duration: 2h	
	-Damp heat, cycle	Sub-clause 4.23.6	
	(12+12hour cycle)	Test method: 2	
	Remaining cycle	Test temperature: 55 °C	
		[Severity (2)]	
		Number of cycles: 5 cycles	
	–D.C. load	Sub-clause 4.23.7	
		The applied current shall be the rated current.	
		Duration: 1 min.	Nie viellele deueene
		Visual examination	No visible damage
		Resistance	$\Delta R \le \pm 5 \%$
10	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: RLP16: Figure-3-1	
		RLP20, MLP20 Figure-3-2	
		RLP32 MLP32 Figure-3-3	
		RLP63, MLP63 Figure-3-4	
	Endurance at 70 °C	Sub-clause 4.25.1	
		Ambient temperature: 70 °C±2 °C	
		Duration: 1000 h	
		The current shall be applied in cycles of 1.5 h on	
		and 0.5 h.	
		The applied current shall be the rated current	
		Examination at 48 h, 500 h and	
		1000 h:	
		Visual examination	No visible damage
		Resistance	$\Delta R \le \pm 5 \%$
11	Mounting	Sub-clause 4.31	
	_	Substrate material: Epoxide woven glass	
		Test substrate: Figure–3–1	
	Variation of resistance with	Sub-clause 4.8	As in Table–1
	temperature	+20 °C / +155 °C	
	i		

RLP16, 20, 32, 63, MLP20,32, 63 Page: 17/24

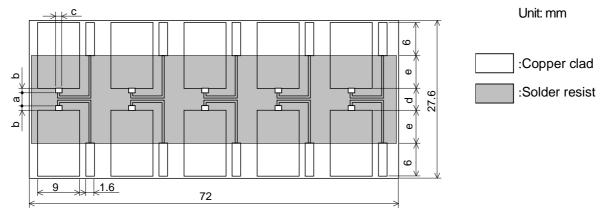
Table-4(5)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
		,	i enormance requirements
12	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure–3–1	
	Damp heat, steady state	Sub-clause 4.24	
		Ambient temperature: 40 °C±2 °C	
		Relative humidity: 93 ⁺² ₋₃ %	
		Without current applied.	
		Visual examination	No visible damage
			Legible marking
		Resistance	ΔR ≤ ±5%
13	Dimensions (detail)	Sub-clause 4.4.3	As in Table-4
	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure–3–1	
	Endurance at upper	Sub-clause 4.25.3	
	category temperature	Ambient temperature:155 °C±2 °C	
		Duration: 1000 h	
		Examination at 48 h, 500 h and	
		1000 h:	
		Visual examination	No visible damage
		Resistance	ΔR ≤ ±5%

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

RLP16, 20, 32, 63, MLP20,32, 63 Page: 18/24

8. Test substrate



Style	Rated resistance (m Ω)	а	b	С	d	е
DI D16	5	0.6	0.9	0.0	2.2	6.0
RLP16	10	1.0	0.6	0.9	2.2	6.2
RLP20	2,3	0.5	1.1	1.36	2.7	5.95
	4 to 10	8.0	0.95	1.30	2.1	5.95
	1	1.0	1.45			
	2	2.1	0.9			
RLP32	3	8.0	1.55	1.7	3.9	5.35
INLF 32	4	1.0	1.45	1.7	3.9	5.35
	5 and 6	1.4	1.25			
	7 to 15	2.1	0.9			
	1	1.5	3.05		7.6	
	2	4.0	1.8			3.5
RLP63	3, 4	1.8	2.9	3.5		
	5	2.4	2.6			
	6 to 15	4.0	1.8			
MLP20	2,3	0.5	1.1	1.36	2.7	5.95
IVILPZU	4 to 10	8.0	0.95	1.30	2.7	5.95
	1	1.0	1.45			
	2	2.1	0.9			
MLP32	3	8.0	1.55	1.7	3.9	5.35
IVILESZ	4	1.0	1.45	1.7	3.9	5.55
	5 and 6	1.4	1.25			
	7 to 10	2.1	0.9			
MIDES	0.5, 2 to 4	1.8	2.9	2.5	7.6	2.5
MLP63	1.5, 5 to 10	4.0	1.8	3.5	0.1	3.5

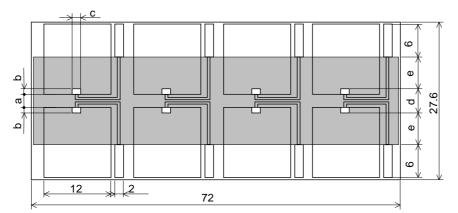
Figure-3-1 RLP16, 20, 32, 63, MLP20,32, 63 TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

RLP16, 20, 32, 63, MLP20,32, 63 Page: 19/24



:銅箔パターン
:ソルダーレジス

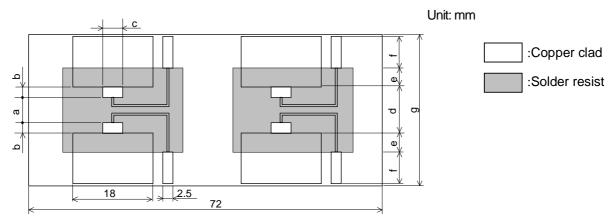
Unit: mm

Style	Rated resistance (m Ω)	а	b	С	d	е
DI DOO	2,3	0.5	1.1			
RLP20	4 to 10	8.0	0.95	1.26	2.7	E OE
MLP20	2,3	0.5	1.1	1.36	2.7	5.95
IVILP20	4 to 10	0.8	0.95			

Figure-3-2 RLP20, MLP20 TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm



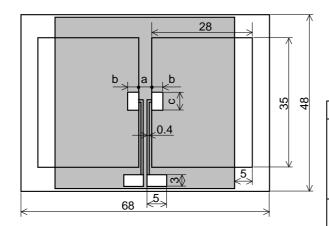
Style	Rated resistance (m Ω)	а	b	С	d	е	f	g
RLP32	1	1.0	1.45	1.7	3.9	5.35	11.68	39
	2	2.1	0.9				6.0	27.6
	3	0.8	1.55				6.0	27.0
	4	1.0	1.45				11.68	39
	5 and 6	1.4	1.25				6.0	27.6
	7 to 15	2.1	0.9				6.0	27.0
MLP32	1	1.0	1.45	1.7	1.7 3.9	5.35	11.68	39
	2	2.1	0.9				6.0	27.6
	3	0.8	1.55				6.0	27.0
	4	1.0	1.45				11.68	39
	5 and 6	1.4	1.25					6.0
	7 to 10	2.1	0.9				0.0	21.0

Figure-3-3 RLP32, MLP32 TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.07mm

RLP16, 20, 32, 63, MLP20,32, 63 Page: 20/24



Unit: mm :Copper clad :Solder resist

No: RLP-K-HTS-0001

Style	Rated resistance (m Ω)	а	b	С
	1	2.0	3.0	4.0
RLP63	2	4.0	1.8	
	3, 4	1.8	2.9	3.5
	5	5 2.4 2.6		3.5
	6 to 15	4.0	1.8	
MLP63	0.5, 2 to 4	1.8	2.9	2.5
	1.5, 5 to 10	4.0	1.8	3.5

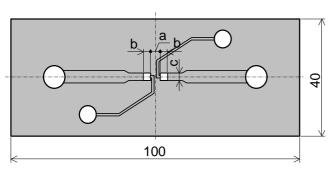
Figure-3-4 RLP63, MLP63 TEST SUBSTRATE

Remark: Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.07mm

Remark: In the case of connection by connector, the connecting terminals are gold plated.

However, the plating is not necessary when the connection is made by soldering.



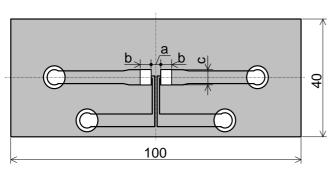
Unit: mm :Copper clad :Solder resist

Style	Rated resistance (m Ω)	а	b	С	
	5	0.6	0.9	0.0	
RLP16	10	1.0	0.6	0.9	
RLP20	2,3	0.5	1.1	1.26	
KLP20	4 to 10	8.0	0.95	1.36	
	1	1.0	1.45		
	2	2.1	0.9		
RLP32	3	8.0	1.55	17	
KLP32	4	1.0	1.45	1.7	
	5 and 6	1.4	1.25		
	7 to 15	2.1	0.9		
MLP20 2,3		0.5	1.1	1.36	
IVILP20	4 to 10	8.0	0.95	1.30	
	1	1.0	1.45		
	2	2.1	0.9		
MLP32	3		1.55	1.7	
	4	1.0	1.45	1.7	
	5 and 6	1.4	1.25		
	7 to 10	2.1	0.9		

RLP16, 20, 32, MLP20 32 BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

Title: METAL-PLATE CHIP RESISTOR; LOW OHM

RLP16, 20, 32, 63, MLP20,32, 63 Page: 21/24



Onit. Min					
:Copper cla					
	:Solder resist				

Style	Rated resistance (mΩ)	а	b	С	
	1	1.5	3.05	4.0	
	2	4.0	1.8		
RLP63	3, 4	1.8	2.9	3.5	
	5	2.4	2.6	3.5	
	6 to 15	4.0	1.8	<u> </u>	
MLP63	0.5, 2 to 4	1.8	2.9	3.5	
IVILPOS	1.5, 5 to 10	4.0	1.8	3.5	

RLP 63, MLP63 BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

Figure-4

Remark. Material: Epoxy resin based as glass fabric(Specified in JIS C 6484).

Thickness: 1.6mm Thickness of copper clad: 0.035mm

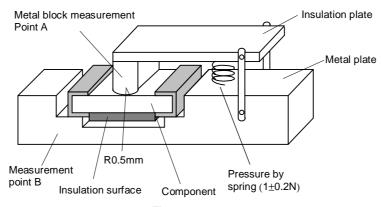


Figure-5

RLP16, 20, 32, 63, MLP20,32, 63

9. Taping

- 9.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010
- 9.2 Taping dimensions
- 9.2.1 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-6 and Table-5.

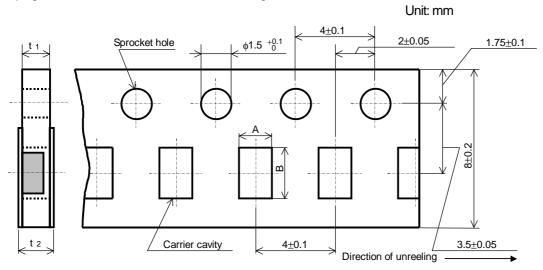


Figure-6

		Table-5		Unit: mm
Style	А	В	t 1	t 2
RLP16	1.15±0.15	1.9 ± 0.2	0.6±0.1	0.8max.
RLP20	1.65±0.15	2.5±0.2	0.6±0.1	0.8max.
MLP20	1.00±0.10	2.0±0.2	0.0±0.1	U.OITIAX.
RLP32	2.00±0.15	3.6±0.2	0.6±0.1	0.8max.
MLP32	2.00±0.13	3.0±0.2	0.0±0.1	U.OITIAX.

9.2.2 Embossed taping (12mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-7 and Table-6.

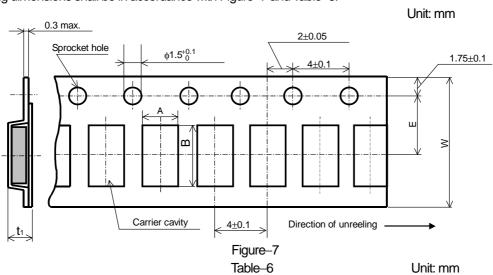


 Table-6
 Unit: mm

 Style
 A
 B
 W
 E
 t₁

 RLP63
 3.6±0.2
 6.9±0.2
 12.0±0.3
 5.5±0.05
 1.1±0.15

RLP16, 20, 32, 63, MLP20,32, 63 Page: 23/24

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following RLP16, 20, 32, MLP20, 32: Figure–8, RLP63, MLP63: Figure–9.
- 6). When the tape is bent with the minimum radius for (RLP16, 20, 32, MLP20, 32: 25mm, RLP63, MLP63: 30mm) the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.

 The maximum number of missing components shall be one or 0.1%, whichever is greater.

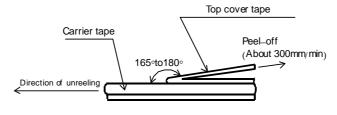


Figure-8

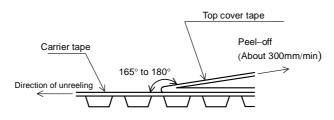
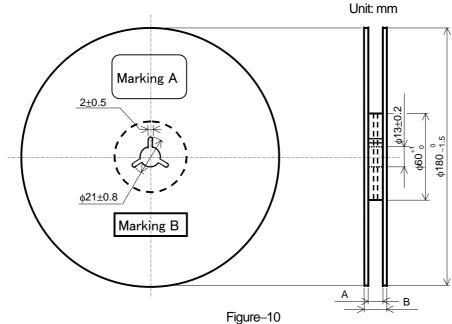


Figure-9

RLP16, 20, 32, 63, MLP20,32, 63 Page: 24/24

9.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure–10 and Table–7. Plastic reel (Based on EIAJ ET–7200C)

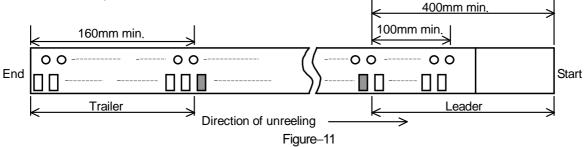


Figure–10 Table–7

	lable−/		Unit: mm
Style	Α	В	Note
RLP16, 20, 32, MLP20,32	9 +1.0	11.4±1.0	Injection molding
1\(\text{Li}\) 10, 20, 32, \(\text{IVILI}\) 20,32	9 0	13±1.0	Vacuum forming
RLP63, MLP63	13 ^{+1.0}	17±1.0	Vacuum forming

Note: Marking label shall be marked on a place of Marking A or two place of Marking A and B.

9.4 Leader and trailer tape.



10. Marking on package

The label of a minimum package shall be legibly marked with follows.

10.1 Marking A

(1) Classification

(Style, Temperature coefficient of resistance, Rated resistance, Tolerance on rated resistance, Packaging form)

(2) Lot number (3) Quantity (4) Manufacturer's name or trade mark (5) Others

10.2 Marking B (KAMAYA Control label)